

# CALL FOR

August 17-20, 2023 Xi'an, Shaanxi, China



## 2023 IEEE 11th International Conference on Information, Communication and Networks

Track

The 2023 IEEE 11th International Conference on Information, Communication and Networks (ICICN) is set to take place in Xi'an, Shaanxi, China during August 17-20, 2023.



All submissions will be peer reviewed. Accepted, registered and presented papers will be published in the ICICN 2023 IEEE conference Proceedings, included in IEEE Xplore and indexed by El Compendex, SCOPUS, etc.

### Wireless/Microwave Power Transmission

Submission Deadline: June 10. 2023

#### **Brief introduction**

With the increasing demand for wireless communication devices in recent years, there has been a need to develop antennas that are flexible, lightweight, and can conform to various shapes and surfaces. Flexible antennas can be used in a variety of applications, including wearable devices, IoT sensors, and medical devices. In this proposal, we present a design and implementation plan for a flexible antenna that can operate in a range of frequencies suitable for wireless communication.

**Topics** Interested topics include (but not limited to):

- Novel designs and materials for flexible antennas
- Modeling and simulation of flexible antennas
- Performance optimization of flexible antennas
- Antenna arrays and beamforming with flexible antennas
- Applications of flexible antennas in biomedical, military, and other fields
- Fabrication techniques for flexible antennas
- Characterization and measurement of flexible antennas
- RF energy harvesting using flexible antennas
- Polarization diversity and MIMO with flexible antennas
- Integration of flexible antennas into wearable devices, IoT, and other applications

#### **Track Chairs and Co-chairs:**

Na Li, Xidian University, China Wei Wang, Xidian University, China

#### Track TPC Members

Tingting Luo, Anhui Medical University, China Runhuai Yang, Anhui Medical University, China Yang Shi, Xidian University, China Nuanyang Cui, Xidian University, China Zongliang Du, Dalian University of Technology, China Wentao Cao, Tongji University, China Kai Ding, Hunan University, China

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